



Product Change Notification / MFOL-26MWUB160

Date:

11-Apr-2024

Product Category:

32-Bit Microcontrollers

PCN Type:

Manufacturing Change

Notification Subject:

CCB 6778 and 6778.002 Initial Notice: Qualification of ANAP as an additional assembly site for selected AT91R40008, ATSAM3NOCA, ATSAM3N1CB, ATSAM3S1CB, ATSAM3S2CA, ATSAM3S4CA, ATSAM3U1CB, AT91SAM7S32C, ATSAM3N00A, ATSAM3N0A, ATSAM3N0AA and ATSAM3N1A device families available in 100L (14x14x1.4mm) and 48L LQFP (7x7x1.4mm) package.

Affected CPNs:

[MFOL-26MWUB160_Affected_CPN_04112024.pdf](#)
[MFOL-26MWUB160_Affected_CPN_04112024.csv](#)

Notification Text:

PCN Status:Initial Notification

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of ANAP as an additional assembly site for selected AT91R40008, ATSAM3NOCA, ATSAM3N1CB, ATSAM3S1CB, ATSAM3S2CA, ATSAM3S4CA, ATSAM3U1CB, AT91SAM7S32C, ATSAM3N00A, ATSAM3N0A, ATSAM3N0AA and ATSAM3N1A device families available in 100L (14x14x1.4mm) and 48L LQFP (7x7x1.4mm) package.

Pre and Post Change Summary:*Applicable for AT91R40008, ATSAM3NOCA, ATSAM3N1CB,*

ATSAM3S1CB, ATSAM3S2CA, ATSAM3S4CA, and ATSAM3U1CB device families in 100L LQFP:

		Pre Change	Post Change	
Assembly Site		ATX Semiconductor (Shanghai) Co. Ltd (ASSH)	ATX Semiconductor (Shanghai) Co. Ltd (ASSH)	Amkor Technology Philippine (P1/P2), INC. (ANAP)
Wire Material		Au	Au	Au
Die Attach Material		2288A	2288A	3230
Molding Compound Material		CEL-9200THF	CEL-9200THF	G631HQ
Lead-Frame	Material	C7025	C7025	C194ESH
	Lead-lock	No	No	Yes
	Paddle Size	180X180	240X240	180X180
See pre and post change for comparison.				

Applicable for AT91SAM7S32C, ATSAM3N00A, ATSAM3N0A, ATSAM3N0AA and ATSAM3N1A device families in 48L LQFP:

		Pre Change	Post Change	
Assembly Site		ATX Semiconductor (Shanghai) Co. Ltd (ASSH)	ATX Semiconductor (Shanghai) Co. Ltd (ASSH)	Amkor Technology Philippine (P1/P2), INC. (ANAP)
Wire Material		Au	Au	Au
Die Attach Material		2288A	2288A	3230

Molding Compound Material		CEL-9200THF	CEL-9200THF	G631HQ
Lead-Frame	Material	C7025	C7025	C194ESH
	Lead-lock	No	No	No
	Paddle Size	197X197	224X224	197X197
		224X224	197X197 mils	
See pre and post change for comparison.				

Impacts to Data Sheet:None

Change Impact:None

Reason for Change:To improve on-time delivery performance by qualifying ANAP as an assembly site.

Change Implementation Status:In Progress

Estimated Qualification Completion Date:May 2024

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive

pre and post change parts.

Time Table Summary:

	January 2024					>	April 2024					May 2024			
	01	02	03	04	05		1 4	1 5	1 6	1 7	1 8	1 9	2 0	2 1	2 2
Initial PCN Issue Date	x							x							
Qual Report Availability													x		
Final PCN Issue Date												x			

Method to Identify Change:Traceability code

Qualification Plan:Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History:January 05, 2024: Issued initial notification.

April 11, 2024: Re-issued the initial notification to include reference CCB 6778.002. Updated the Notification subject, Description of change and Pre and Post change summary table to include AT91SAM7S32C, ATSAM3N00A, ATSAM3N0A, ATSAM3N0AA and ATSAM3N1A device families. Updated the affected CPN list to include CPNs within the scope of CCB 6778.002. Updated Pre and Post Change summary to include lead frame drawing for 48L LQFP (7x7x1.4mm) package.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_MFOL-26MWUB160 Pre and Post_Change_Summary.pdf](#)

[PCN_MFOL-26MWUB160_Qual_Plan.pdf](#)

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

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